

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of  
John HECK

Serial No. 10/611,334      Group Art Unit: 2823

Filed: June 30, 2003      Examiner: LEE, Hsien Ming

For:    MEMS PACKAGING USING A NON-SILICON SUBSTRATE  
         FOR ENCAPSULATION AND INTERCONNECTION

Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT UNDER 37 C.F.R. § 1.111**

Sir:

In response to the Office Action mailed on March 8, 2007, please  
amend the above-identified application as follows: